

D	2017-5				
E	2020-11-28	7	5 30000 7 42000 13" ×15 13" ×12		

描述 / Descriptions

0.8A

MBS

0.8A Surface Mount Glass Passivated Bridge Rectifier, MBS package.

特征 / Features

100V~1000V

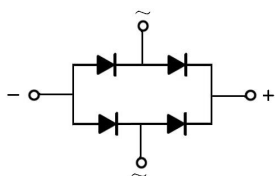
0.8A

Glass Passivated Chip Junction, Reverse Voltage:100to1000V, Forward Current:0.8 A, High Surge Current Capability, Designed for Surface Mount Application.Halogen free product.

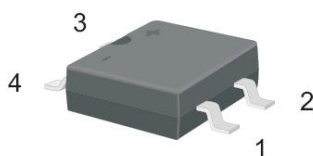
用途 / Applications

General purpose.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



印章代码 / Marking

See Marking Instructions.



极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating						单位 Unit
		MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_a = 50^\circ\text{C}$	I_o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	30						A
Typical Junction Capacitance ^(Note1)	C_j	13						pF
Typical Thermal Resistance ^(Note2)	$R_{\theta JA}$	95						$^\circ\text{C/W}$
Typical Thermal Resistance ^(Note2)	$R_{\theta JL}$	30						$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150						$^\circ\text{C}$

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5\text{mm}^2)$ copper pad..

电性能参数 / Electrical Characteristics(Ta=25°C)

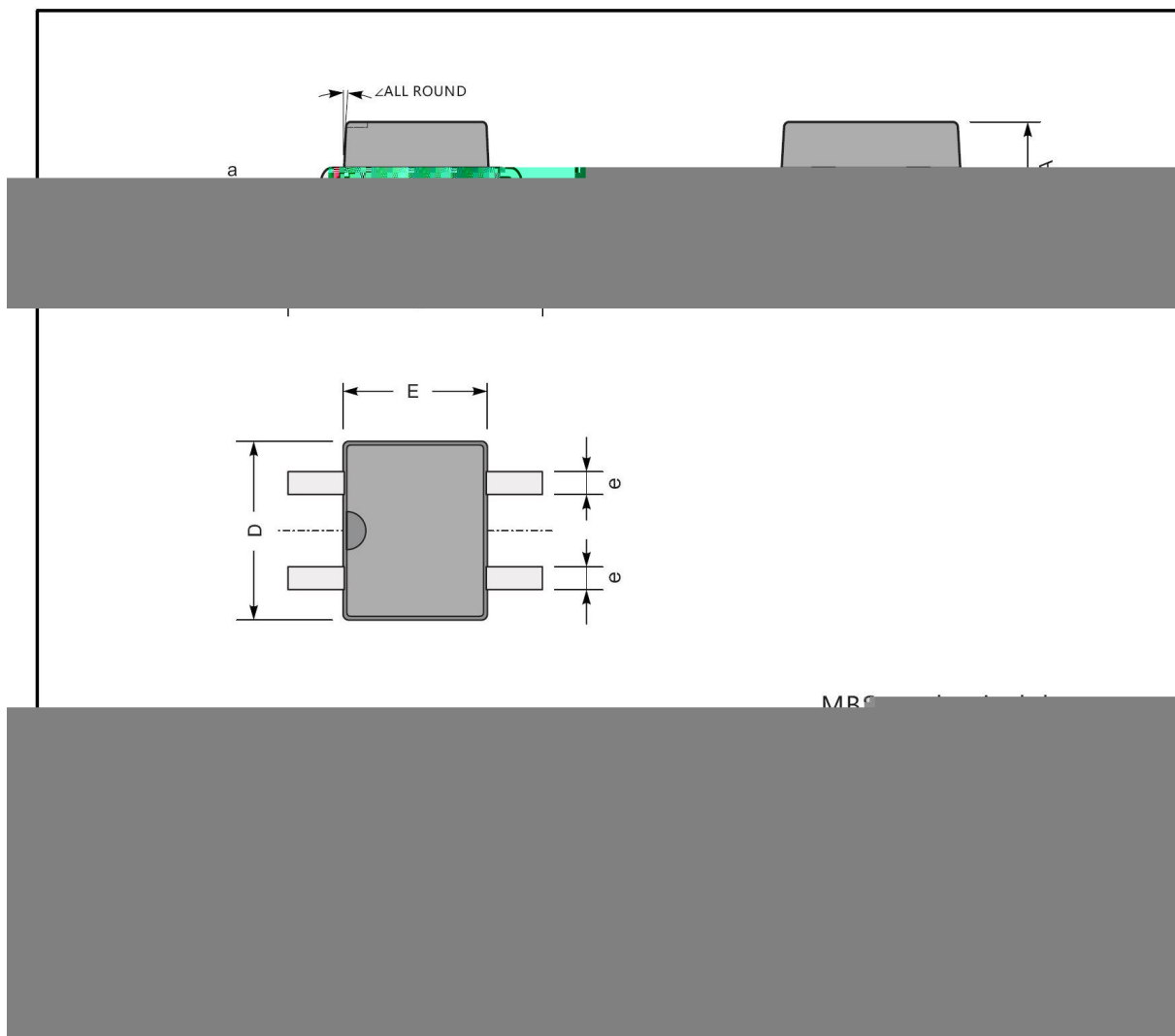
参数 Parameter	符号 Symbol	测试条件 Test condition	数值 Rating	单位 Unit
Maximum Forward Voltage	V_F	$I_F=0.4\text{A}$	1.0	V
		$I_F=0.8\text{A}$	1.1	
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^\circ\text{C}$ $T_a=125^\circ\text{C}$	5.0 40	μA

MB1S~MB10S

Rev.E

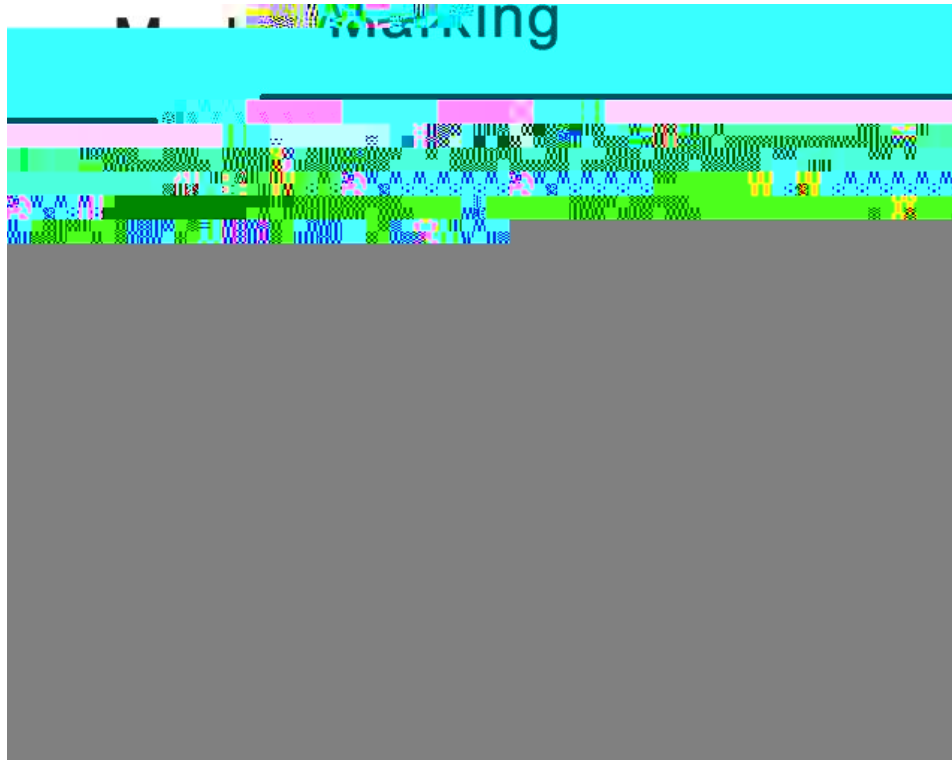
外形尺寸图 / Package Dimensions

MBS





印章说明 / Marking Instructions



印章说明 / Marking Instructions



MB1S

1 *

3 *

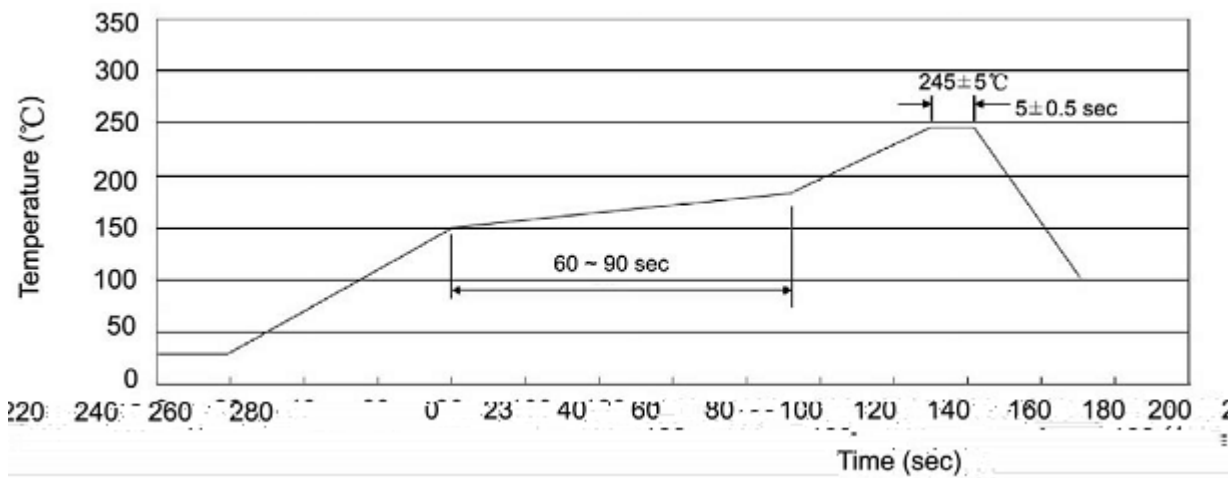
Note:

MB1S Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot
No Code



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|--|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150°C, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260±5°C 10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱
MBS	3000	2	6000	7	42000	13" ×12	336X336X40	380X335X366

使用说明 / Notices